

Chapter 10

Memory & Simple I/O Interfacing

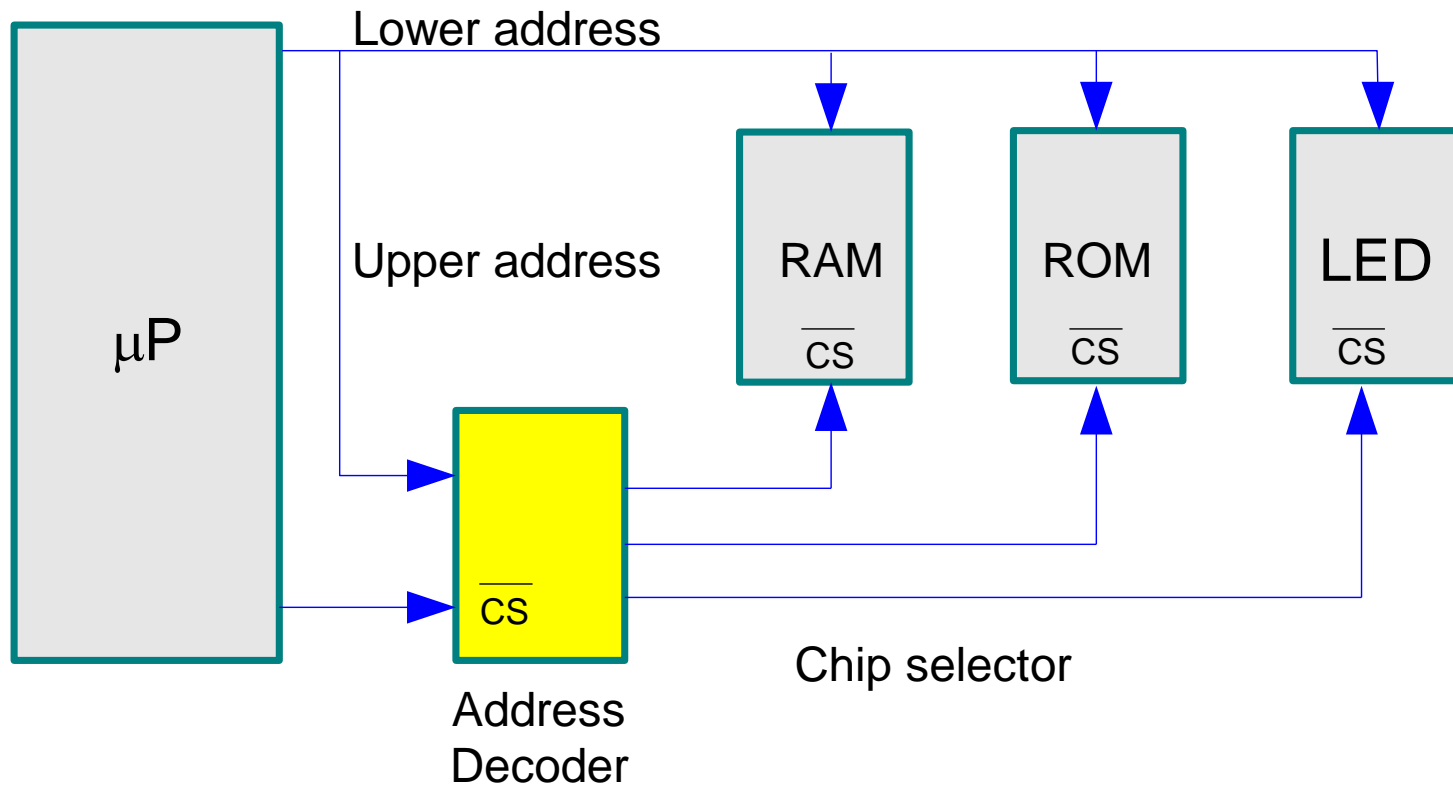
Expected Outcomes

- Explain the importance of tri-state devices in microprocessor system
- Distinguish basic type of semiconductor memory and their applications
- Relate the address and data bus for various memories
- Describe I/O interfacing concept such as I/O driver and memory mapped
- Relate the role of latch and buffer in interfacing with simple I/O devices

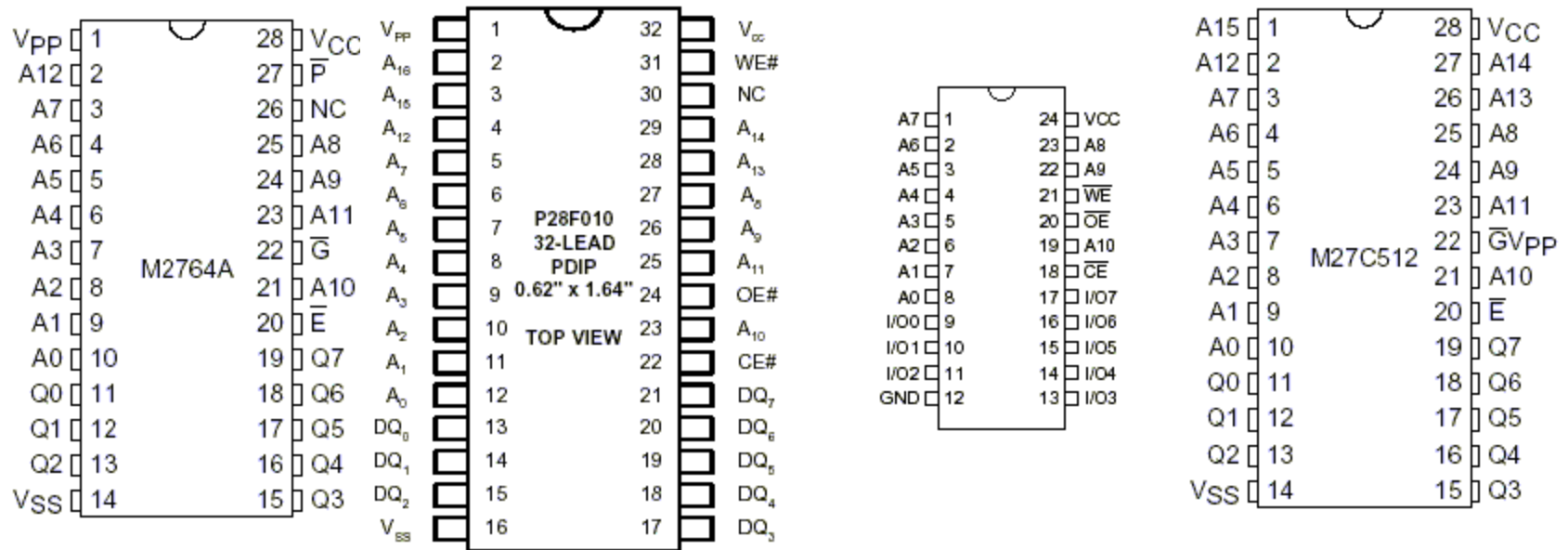
Tri-state Devices

- Any devices connected to a microprocessor should configure in **tristate**
- This is because only **one device** can communicate with the processor at one time leaving other devices at high impedance
- Devices with tristate outputs have an **enable input** such as OE , CS , E , etc
- With this configuration, there will not be any devices fighting for control of common wire which may cause damaging to current flow
- Common devices connected to μP
- Address decoder
 - **Memory** (ROM/RAM)
 - **Input** devices such as keyboard, mouse, switch etc
 - **Output** devices such as printer, monitor, LED, LCD

Tri-state Devices



Memory



Memory

- Memory system is used to store data and instruction
- Type of memory
 - **ROM (Read Only Memory)**
 - Nonvolatile – data remains even the power is off
 - Normally used to store vectors, self-test routine, monitor program, common subroutine and etc
 - Special device is required to store program in ROM
 - **RAM (Random Access Memory)**
 - Volatile type as data are lost as the power is off
 - Temporary storage and normally used for operation and application system



ROM

■ Programmable Maskable ROM

- Very cheap and normally is programmed in factory for mass production
- One-time written and widely used in game cassette

■ Programmable ROM (PROM)

- One-time written and can be programmed by using PROM programmer

■ One-time PROM (OTPROM)

- Cheap version of PROM with plastic packed

ROM

■ Flash Memory

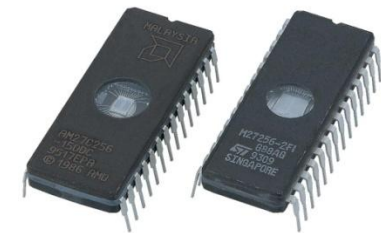
- Like EEPROM, but erasing process involves block-by-block
- Common in digital camera & MP3



EPROM

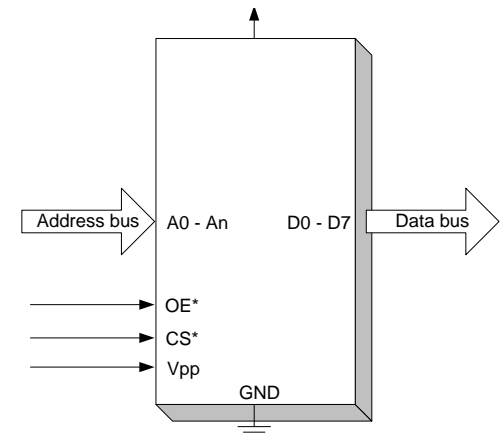
Common industrial EPROM

■ 2716	2 kbyte (2048 x 8 bits)
■ 2732	4 kbyte (4096 x 8 bits)
■ 2764	8 kbyte (8192 x 8 bits)
■ 27128	16 kbytes (16384 x 8 bits)
■ 27256	32 kbytes (32768 x 8 bits)



Common industrial EEPROM

■ 2816	2 kbyte (2048 x 8 bits)
■ 2864	8 kbyte (8192 x 8 bits)



EPROM

Part No	Capacity	Org	Access	Pins	Vpp
2716	16K	2Kx8	450ns	24	25V
2732	32K	4Kx8	450ns	24	25V
27C32-1	32K	4Kx8	450ns	24	25V CMOS
2764-20	64K	8Kx8	200ns	28	21V
27C64-12	64K	8Kx8	120ns	28	12.5V CMOS
27128-25	128K	16Kx8	250ns	28	21V
27C256-15	256K	32Kx8	150ns	28	12.5V CMOS
27C512-15	512K	6Kx8	150ns	28	12.5V CMOS
27C010-15	1024K	128Kx8	150ns	32	12.5V CMOS
27C020-15	2048K	256Kx8	150ns	32	12.5V CMOS
27C040-15	4096K	512Kx8	150ns	32	12.5V CMOS

EEPROM & Flash Chip

■ Some common EEPROM

Part No	Capacity	Org	Speed	Pins	Vpp
2816A-25	16K	2Kx8	250ns	24	5V
2864A	64K	8Kx8	250ns	28	5V
28C64A-25	64K	8Kx8	250ns	28	5V CMOS
28C256-15	256K	32Kx8	150ns	28	5V

■ Some common Flash Chips

Part No	Capacity	Org	Speed	Pins	Vpp
28F256-20	256K	32Kx8	200ns	32	12V CMOS
28F010-15	1024K	128Kx8	150ns	32	12V CMOS
28F020-15	2048K	256Kx8	150ns	32	12V CMOS

EPROM Pin Function

■ **A0–An (Address Bus)**

- Address bus directly connected to lower address of microprocessor

■ **D0–Dn (Data Bus)**

- Data bus directly connected to data bus

■ **CS* (Chip Select)**

- To activate EPROM and connected to address decoder

■ **OE* (Output Enable)**

- ROM place data into data bus

EPROM Pin Function

■ Vpp

- Used by EPROM programmer to change bit in the chip
- Place into high when it is not used

CS*	OE*	Functions
1	0	IC disable with minimum power consumption
1	1	IC disable with minimum power consumption
0	0	Read mode; data are placed on data bus
0	1	Wait state mode; data are placed on the bus when OE* is activated

EPROM Memory Chip

Examples of Parallel EPROMs

	2716	2732	2764	27128	27256	27512		2716	2732	2764	27128	27256	27512
1			Vpp	Vpp	Vpp	A15	28			Vcc	Vcc	Vcc	Vcc
2			A12	A12	A12	A12	27			PGM	PGM	A14	A14
3	A7	A7	A7	A7	A7	A7	26	Vcc	Vcc	N.C	A13	A13	A13
4	A6	A6	A6	A6	A6	A6	25	A8	A8	A8	A8	A8	A8
5	A5	A5	A5	A5	A5	A5	24	A9	A9	A9	A9	A9	A9
6	A4	A4	A4	A4	A4	A4	23	A11	A11	A11	A11	A11	A11
7	A3	A3	A3	A3	A3	A3	22	OE*	OE*	OE*	OE*	OE*	OE*/Vpp
8	A2	A2	A2	A2	A2	A2	21	A10	A10	A10	A10	A10	A10
9	A1	A1	A1	A1	A1	A1	20	CE	CE	CE	CE	CE	CE
10	A0	A0	A0	A0	A0	A0	19	D7	D7	D7	D7	D7	D7
11	D0	D0	D0	D0	D0	D0	18	D6	D6	D6	D6	D6	D6
12	D1	D1	D1	D1	D1	D1	17	D5	D5	D5	D5	D5	D5
13	D2	D2	D2	D2	D2	D2	16	D4	D4	D4	D4	D4	D4
14	GND	GND	GND	GND	GND	GND	15	D3	D3	D3	D3	D3	D3

RAM

- Two basic types of RAM

- **Static RAM (SRAM)**

- Easy to be used and requires an internal flip-flop to store each bit
- Need 4 – 6 transistor for each FF and suitable for small system
- 4 times compact than DRAM with the same size
- Normally used in personal computer

- **Dynamic RAM (DRAM)**

- Cheaper as dynamic RAM uses a single transistor that acts like a charged capacitor to store each bit
- Since the charge leaks, a DRAM must use refresh circuit to recharge the capacitor periodically (typically every 2 ms)

RAM & NVRAM

■ Performance difference

- DRAM contain more data per chip size
- SRAM is faster and simpler
- **NV-RAM (Non-volatile RAM)** is introduced to allow the CPU to read and write to it and not lost the content even the power is turned off
- To retain the content, the NVRAM chip internally
 - Uses extremely power efficient – CMOS
 - Uses an internal lithium battery as backup energy
 - Uses intelligent control circuitry to monitor V_{CC} pin and activates internal power if needed
- Thus the NV-RAM is expensive because it must provide the facilities in a single IC

SRAM & DRAM

■ Examples of SRAM & DRAM

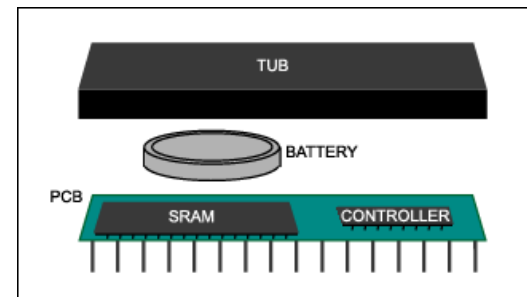
Part No	Capacity	Org	Speed	Pins	Vpp
6116P-1	16K	2Kx8	100ns	24	CMOS
6116LP-3	16K	2Kx8	150ns	24	CMOS
6264P-10	64K	2Kx8	100ns	28	CMOS
62256LP-10	256K	32Kx8	100ns	28	Low Power CMOS
62256LP-12	256K	32Kx8	120ns	28	Low Power CMOS

Part No	Capacity	Org	Speed	Pins
4164-15	64K	64Kx1	150ns	16
41256-15	256K	256Kx1	150ns	16
511000P-8	1M	1Mx1	80ns	18

NVRAM

■ NV-RAM from Dallas Semiconductor

Part No	Capacity	Org	Speed	Pins
DS1220Y-150	16K	2Kx8	150ns	26
DS1225AB-150	64K	8Kx8	150ns	28
DS1230Y-85	256K	32Kx8	85ns	28



RAM

■ Common industrial RAM

■ 6116

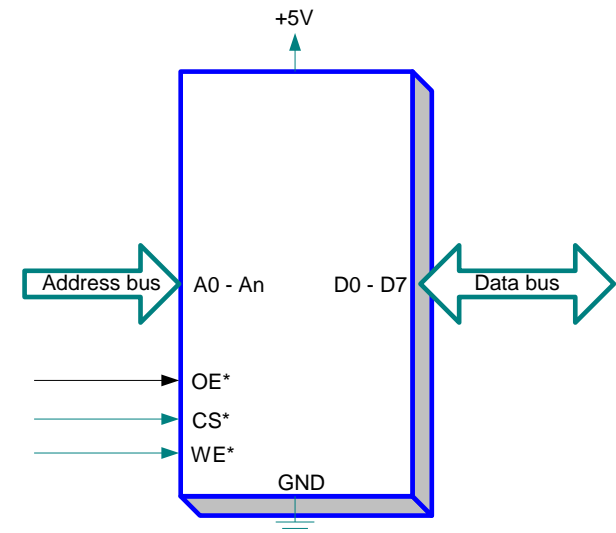
2 kbyte (2048 x 8 bits)

■ 6164/6264

8 kbyte (8192 x 8 bits)

■ 43256/6625

32 kbytes (32768 x 8 bits)



RAM

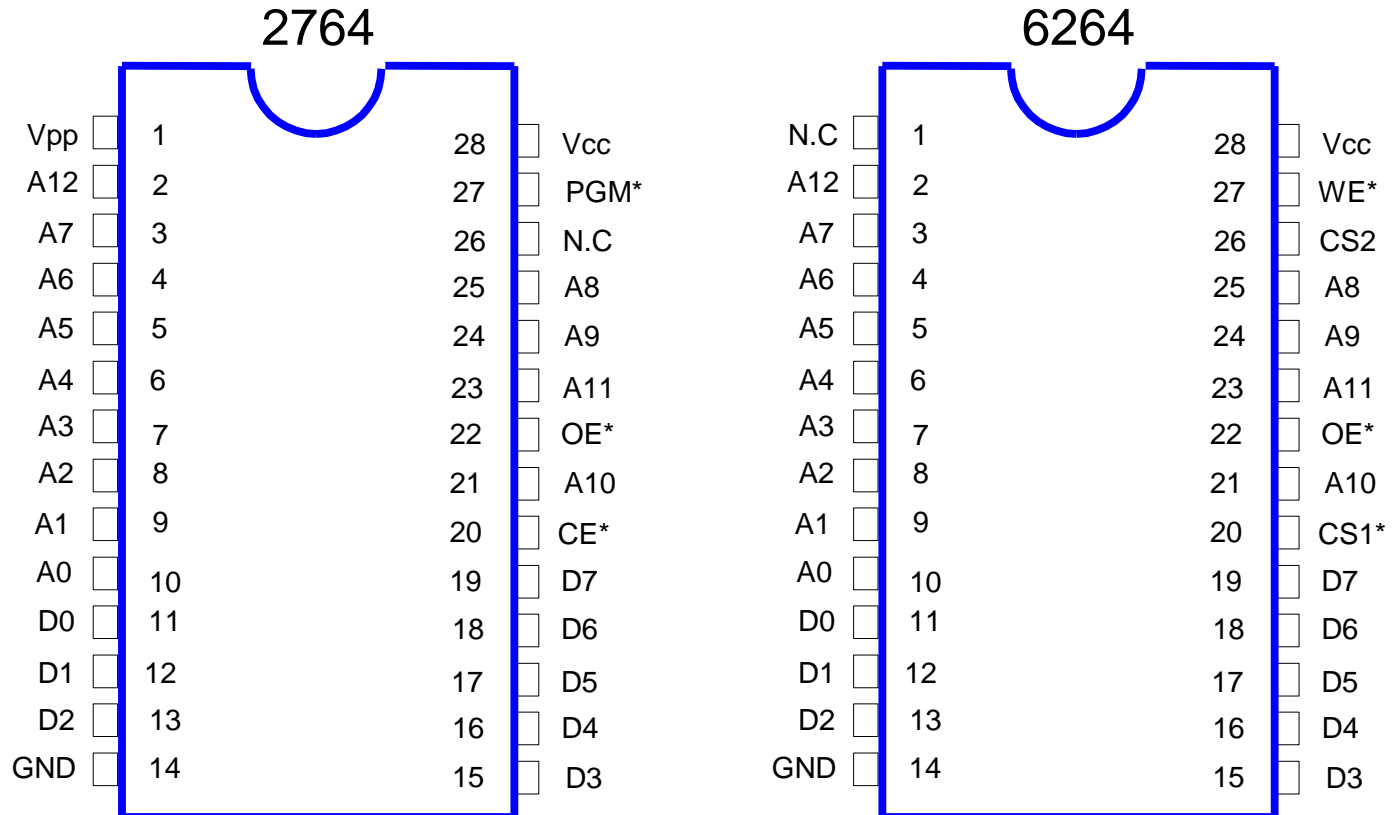
- **A0 – An (Address Bus)** - Address bus directly connected to lower address of microprocessor
- **D0 – Dn (Data Bus)** - Data bus directly connected to data bus
- **CS*** (Chip Select) - To activate EPROM and connected to address decoder
- **OE*** (Output Enable) - RAM places data into data bus
- **WE*** (Write Enable) - RAM stores data into cell

RAM

■ The role of CS^* , OE^* and WE^*

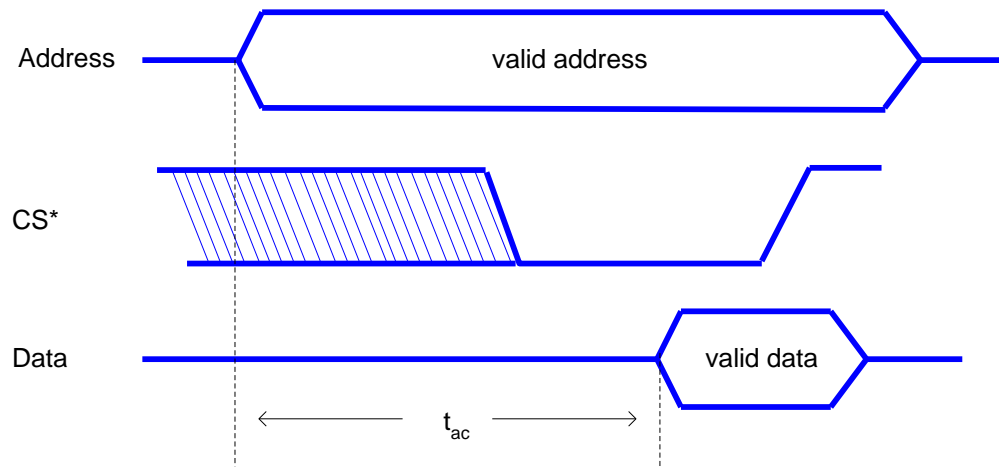
CS^*	OE^*	WE^*	Functions
1	X	X	IC disable with minimum power consumption
0	0	0	Undefined
0	0	1	Read mode; data are placed on data bus
0	1	0	Write mode; data are latched
0	1	1	Wait state mode

2764 vs 6264

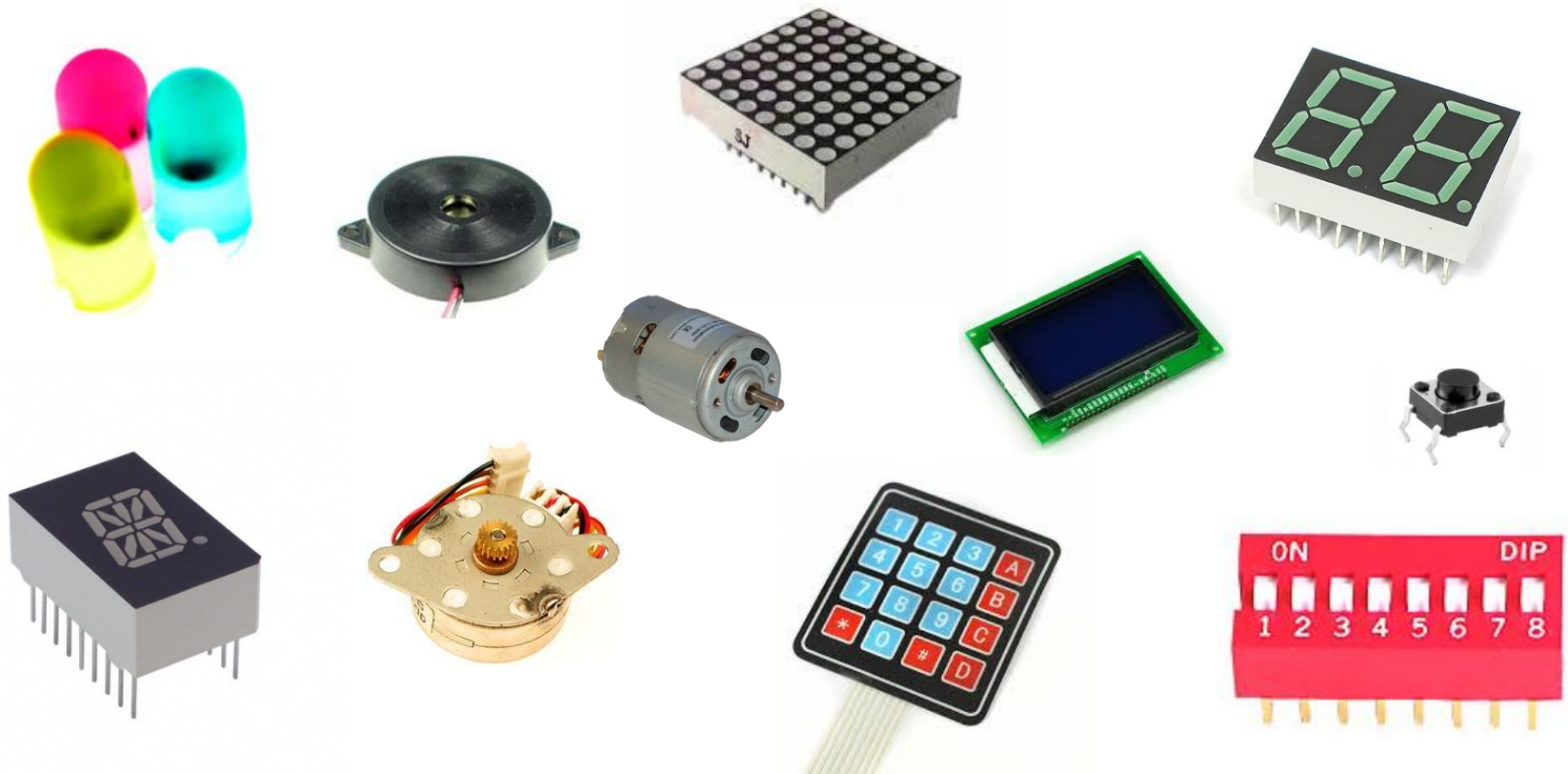


Access Time

- The performance of memory chips normally are based on access time
- **Access time (t_{ac})** is defined as time taken for the memory to place data onto the data bus as the read signal is received

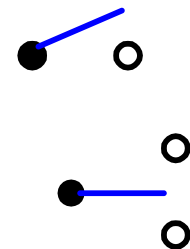
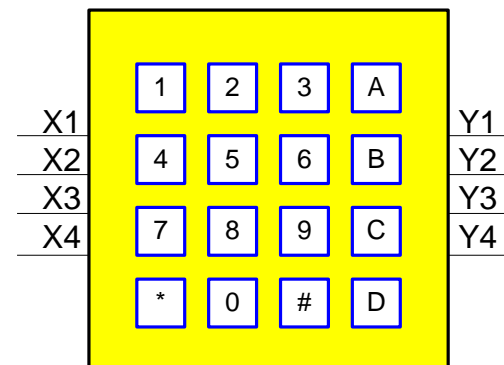
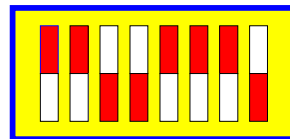
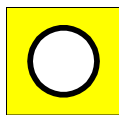


Simple I/O Devices



Input Devices

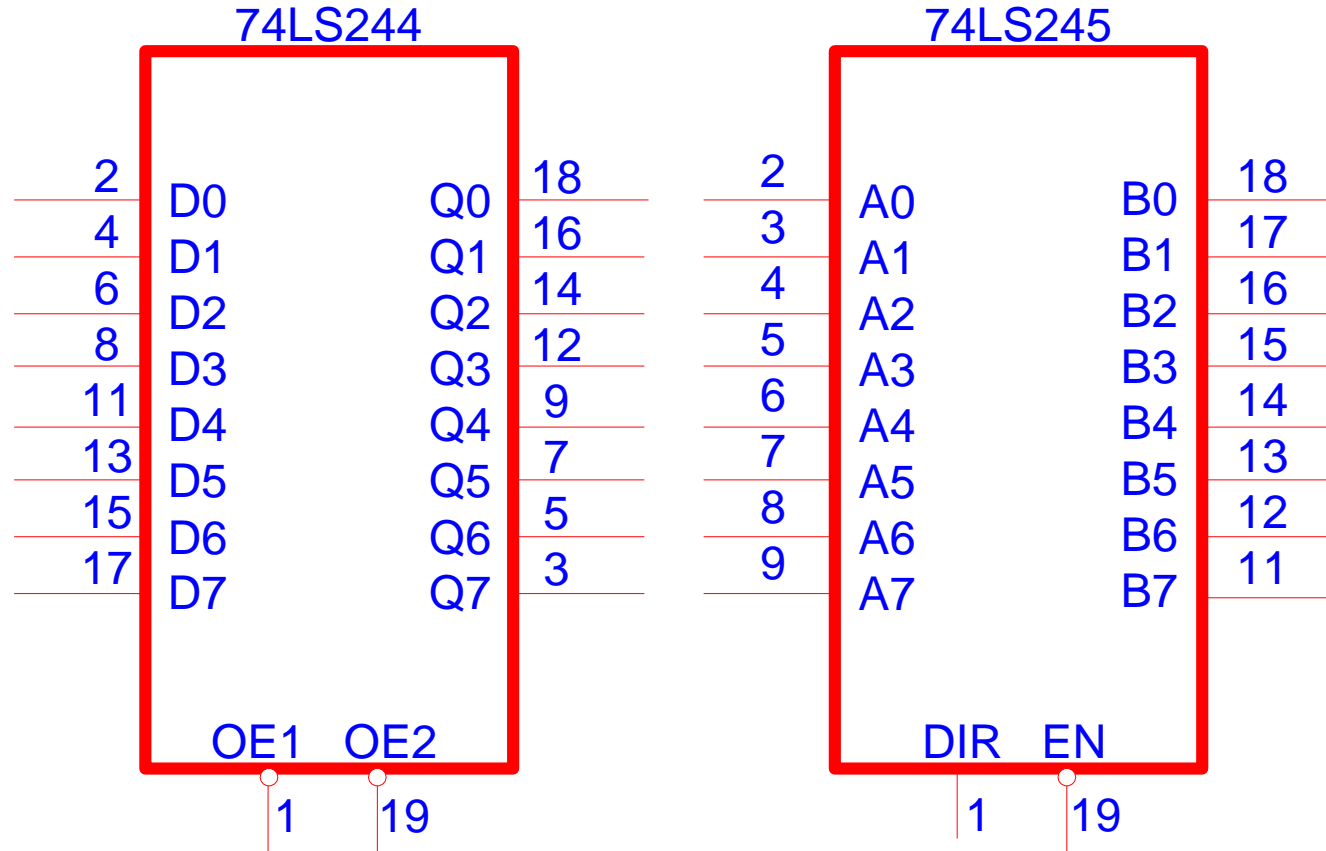
- Most input devices do not possess the tristate configuration
- Normally they are connected to other tristate devices such as buffer to ensure proper interface with μP
- Common input devices
 - Switches (reset, SPST, SPDT etc)
 - Keypad
 - Sensors



Buffer

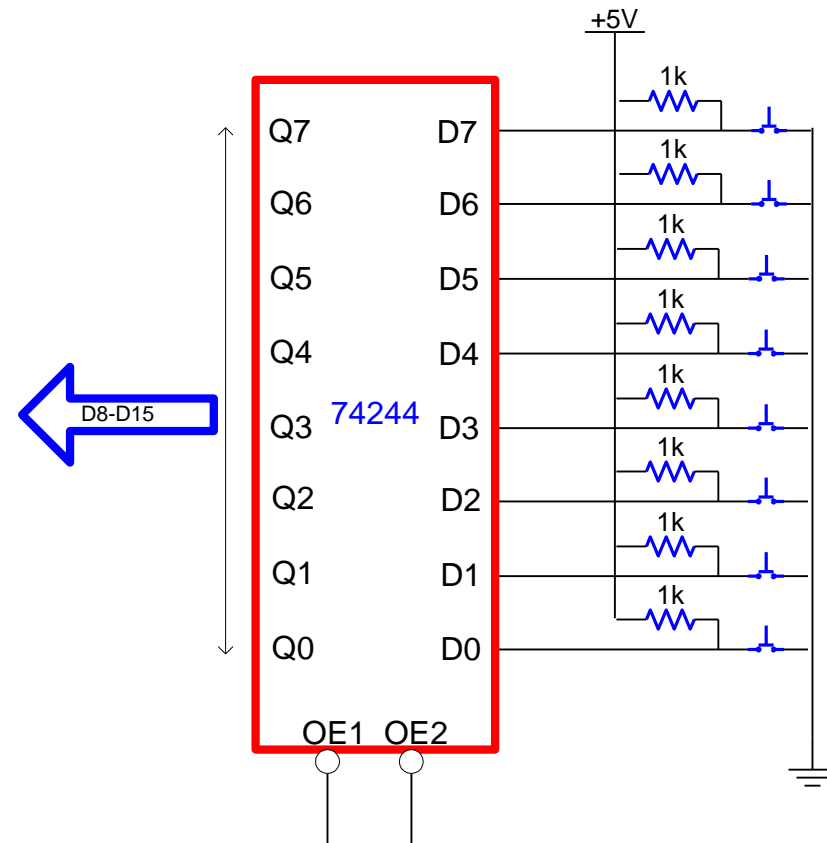
- Buffer is a circuit that allows any logics onto the data bus
- **74LS244 unidirectional tri-state buffer**
 - If $OE=0$, input is allowed to pass through
 - If $OE=1$, output is placed in high impedance
- **74LS245 bidirectional buffer**
 - A.k.a transceiver
 - Data direction is determined by DIR
 - If $DIR=0$, data movement is from A to B
 - If $DIR=1$, data movement is from B to A

Buffer



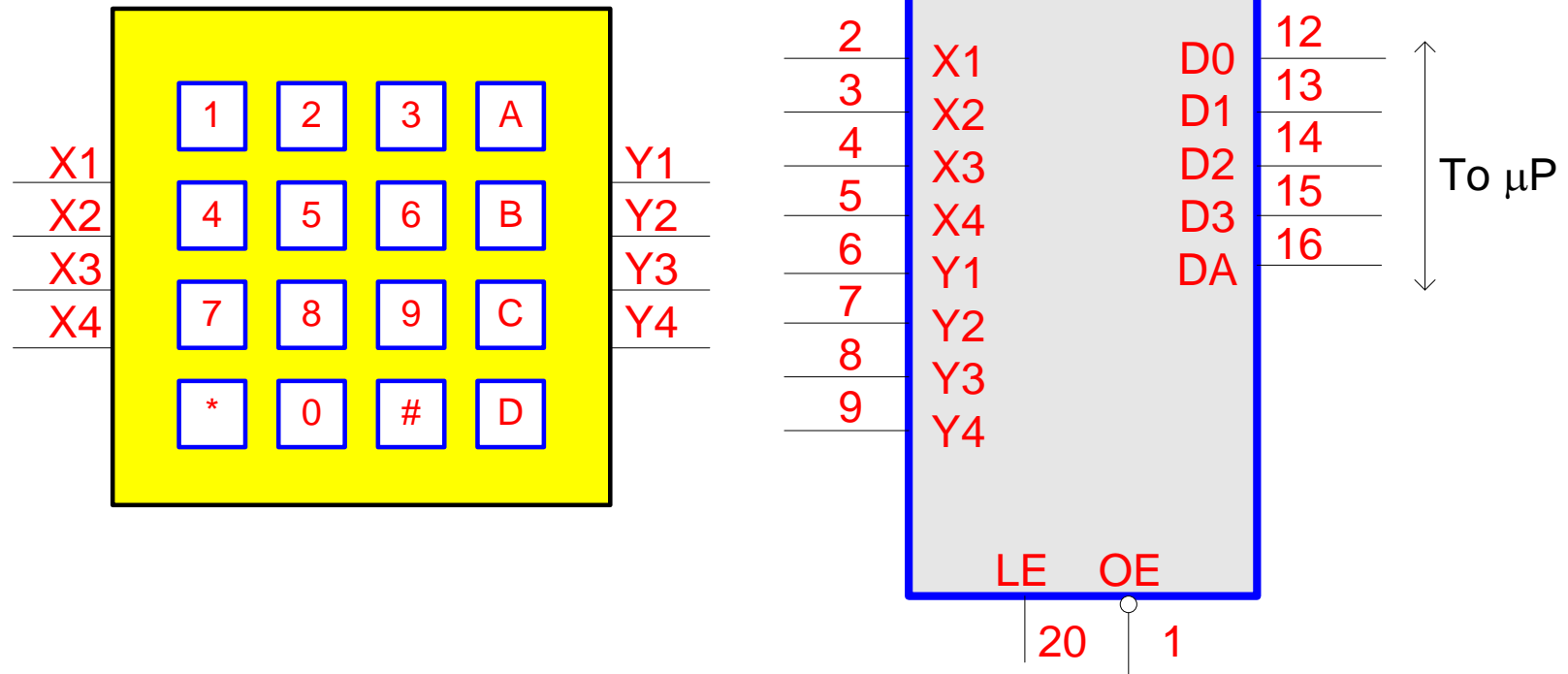
Simple Input Interface

- Simple inputs connection with a buffer
- Enable pins (OE1^* & OE2^*) will activate the buffer and normally are connected to address decoder



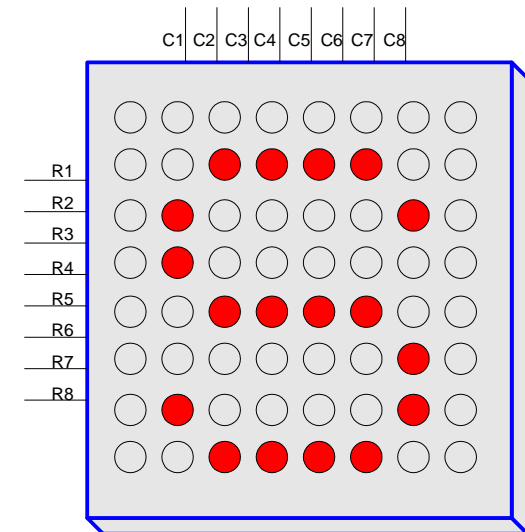
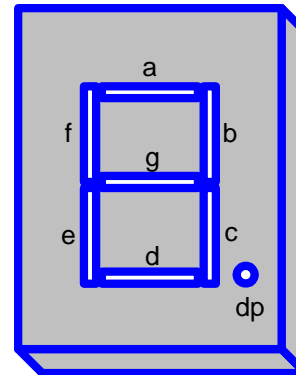
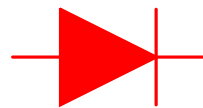
Keypad Encoder

- When a keypad is used in a system, a keypad encoder (74922) is required to facilitate the program



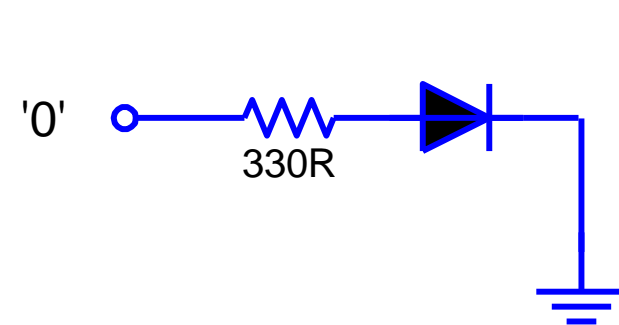
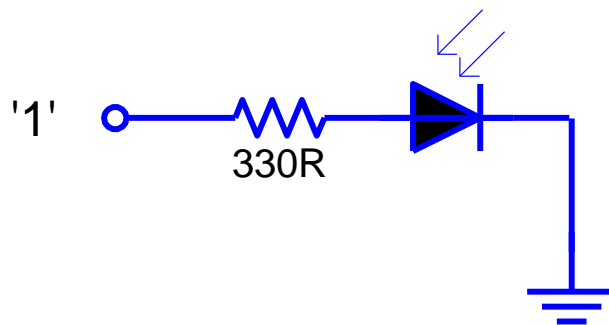
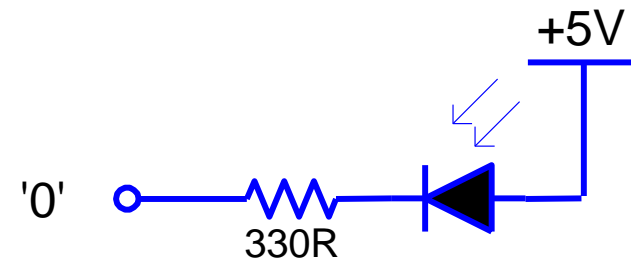
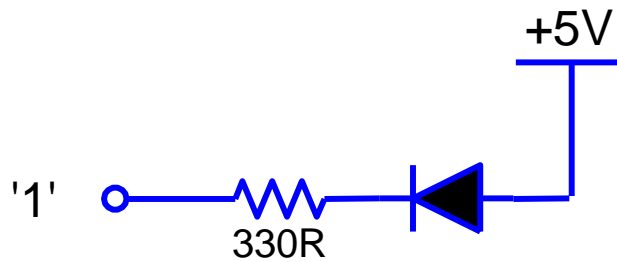
Output Devices

- Like input devices, output devices do not possess the tristate configuration
- They are connected to other tristate devices such as latch for proper interface with processor
- Common output devices
 - Light Emitting Diode (LED)
 - Seven Segment Display
 - Dot Matrix



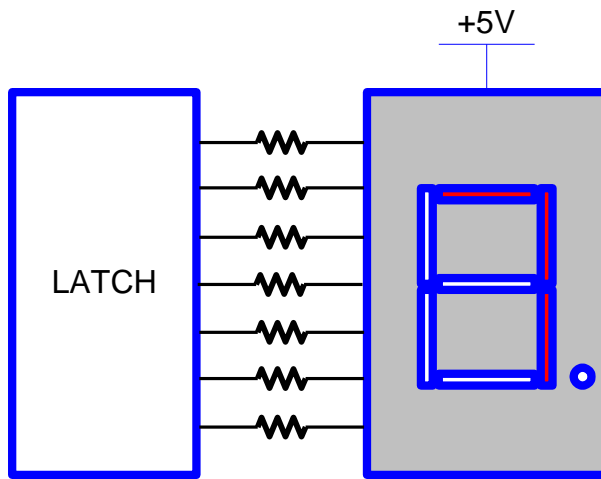
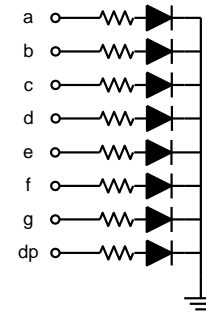
LED

- LED is the most common output device used in microprocessor-based system due its simplicity & cost

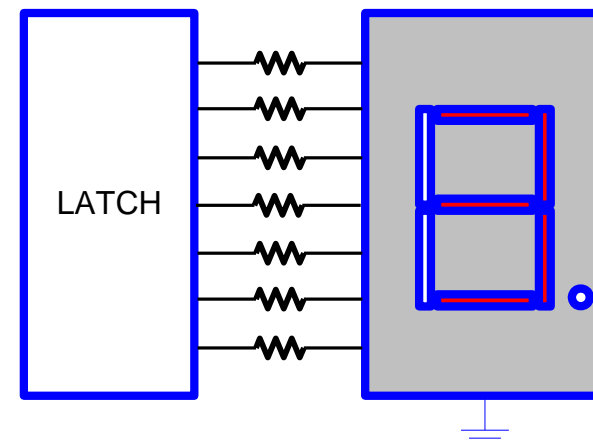


7-Segment Display

- There two type configurations
 - Common Anode
 - Common Cathode



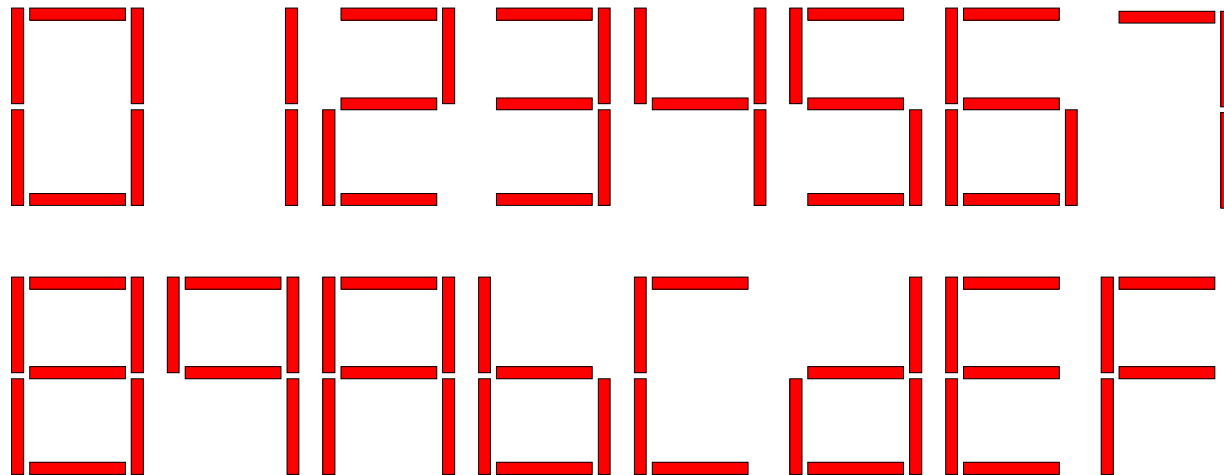
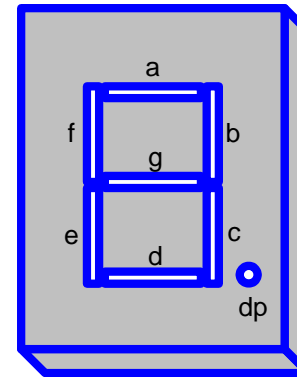
Common Anode



Common Cathode

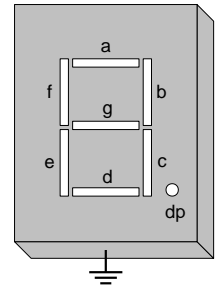
7-Segment Display

- Common Cathode
- Common Anode



7-Segment Display

■ Common Cathode



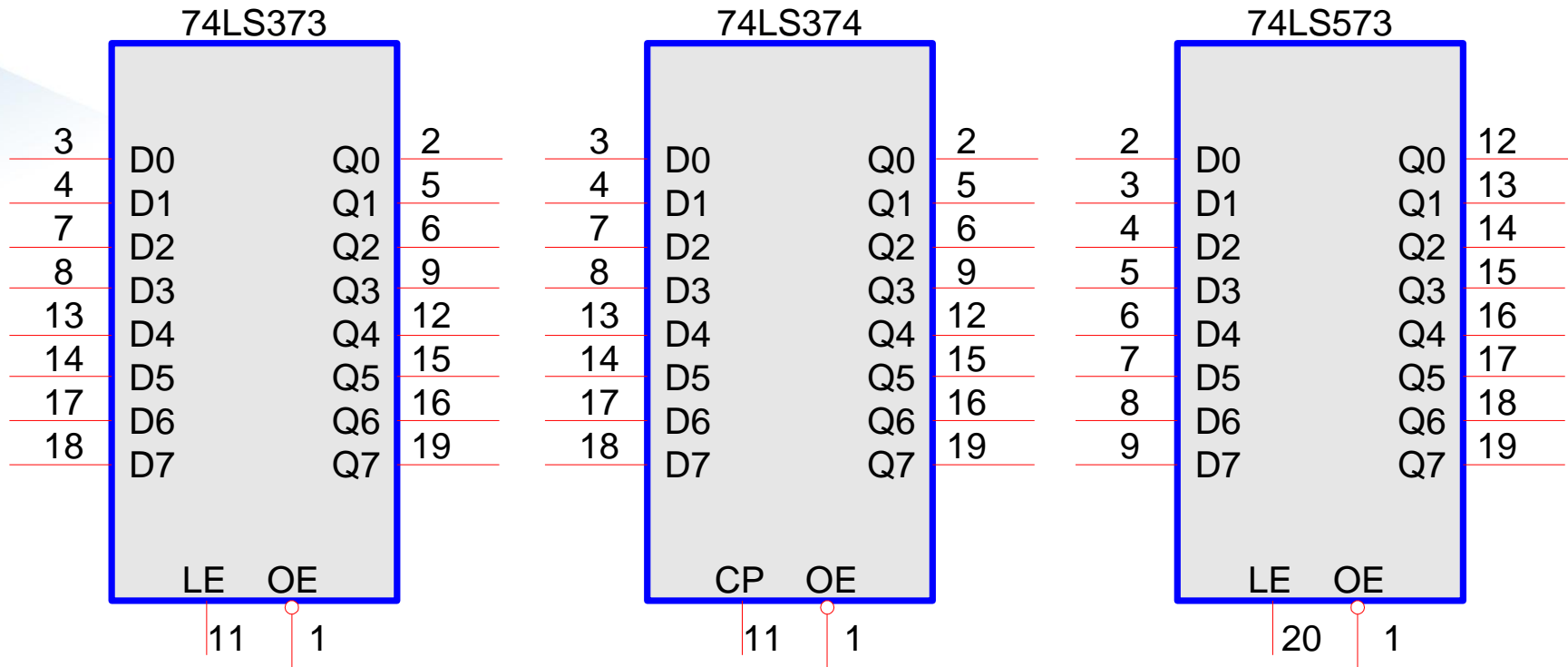
	a	b	c	d	e	f	g
0	1	1	1	1	1	1	0
1	0	1	1	0	0	0	0
2	1	1	0	1	1	0	1
3	1	1	1	1	0	0	1
4	0	1	1	1	0	0	1
5	1	0	1	1	0	1	1
6	1	0	1	1	1	1	1
7	1	1	1	0	0	0	0

	a	b	c	d	e	f	g
8	1	1	1	1	1	1	1
9	1	1	1	0	0	1	1
A	1	1	1	0	1	1	1
B	0	0	1	1	1	1	1
C	1	0	0	1	1	1	0
D	0	1	1	1	1	0	1
E	1	0	0	1	1	1	1
F	1	0	0	0	1	1	1

Latch

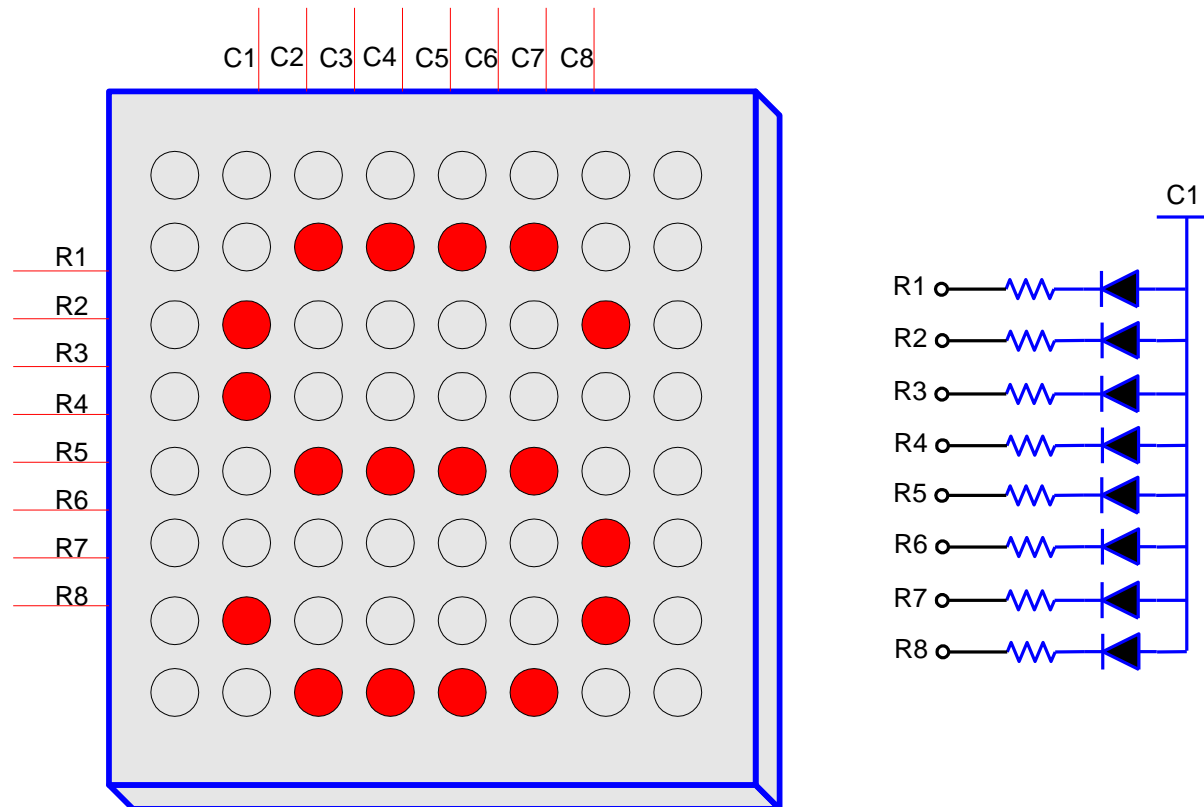
- Latch is a circuit that capture value at the input
- **74LS373 transparent latch**
 - During $LE=1$, $Q=D$
 - During $LE=0$, Q hold D during negative edge
 - Another version is 74LS573 where the difference is in pin configuration
- **74LS374 edge triggering**
 - During positive transition at CP , data is transferred from D to Q
 - Another version is 74LS574 where the difference is in pin configuration

Latch



Dot Matrix

- A multi-purpose output display, dot matrix is another common output device



Self-Test

- Determine the number of address pins and memory capacity of the following EPROM

Part No	Capacity (bytes)	Address Pins
TMS27C64		
HD2716		
NM27C128		
62256LP-10		
27C010-15		
27C040-15		
27512-25		

Self-Test

■ Exercise

For ROM chip 27128, find the number of data and address pins. In your opinion what is the minimum pin configuration of the chip

■ Exercise

Discuss the number of pins for addresses in (i) 2 kbytes RAM (ii) 512 bytes of RAM

■ Exercise

Explain the difference between EEPROM and flash memory

■ Exercise

Which memory is used as cache memory in the PC?

Self-Test

■ Exercise

Explain the role of OE^* , CS^* , WE^* pins in RAM

■ Exercise

Why do we need to use latch instead of connecting the output device (such as 7-segment display) directly to the CPU?

■ Exercise

What is access time for a memory? Briefly describe the important of fast access time in a microprocessor system by giving an example